

## Model LH836 Automatic Back Grinding Wafer Taper

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### **Feature**

- Mounting Method: Non contact type pure vacuum mounting, Nothing touches wafer except tape and edge support.  
No roller is required, no more difficult alignment of roller/wafer parallelism roller cleaning, and no pressure variation on wafer due to different thickness.  
Absolutely no air bubble and better adhesion.
- Tape Tension: Controlled and programmable.
- Mounting Temperature: Room temperature to 150° C.
- Wafer Handler: Laser guided detection.  
Misplaced wafer in cross slot is detected and alarm on.  
To prevent wafer breakage, handler fork is cleared of cassette during cassette indexing between slots.  
Wafer centering and flat/notch detected by laser sensor.  
High accuracy XY $\theta$  motion, XY resolution at 0.0004",  $\theta$  resolution at 0.1125°.
- Tape Cutting: 3 axis (2 rotary & 1 linear) motor control.  
Heated blade up to 150° C.
- Fast Conversion: Less than 5 minute between converting 4", 5", 6" & 8" wafer.
- ESD Protection: 2 Ionizers are installed beneath the adhesive tape and above wafer chamber to remove any static charge generated.
- Machine Safety: Doors are interlocked with EMO.
- Vacuum Supply: Integrated vacuum pump is standard on machine. No need for line vacuum facilities.
- No of Cassette: Dual cassette in horizontal, allowing loading/unloading of cassette without stopping machine.
- Control: Standard industrial PC.  
Easy to use menu programming.  
Almost unlimited hard disk and floppy disk storage.  
Color monitor display.

### **Specification**

- Wafer Size: 4", 5", 6" and 8".
- Tape Width: 9" or 230 mm.
- Tape Length: 100 or 200 M.
- Tape Type: Back grinding tape, UV and non UV tape.
- Capacity: 70-80 UPH.
- Power: 220V AC 50/60 Hz. 15A
- Compressed Air: 60 psi dry clean air, 2 CFM.
- Dimension: 1145 mm (W) x 1145 mm (D) x 1710 mm (H).
- Net Weight: 450 Kg.